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PATENT
YOR920030206US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

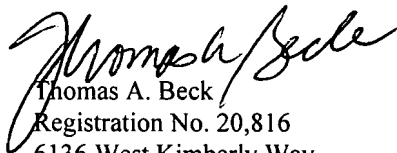
In re Application of : Larry Shungwei Mok
Serial Number : 10/784,624
Filing Date : February 23, 2004
Examiner : Tho V. Duong
Group Art Unit : 3753
For : HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR STRUCTURES

TO: The Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

In response to the Official Action dated October 17, 2007, which was a requirement for restriction, Applicant hereby elects "Species A" of Figures 1 - 3 which are covered in Claims 1 - 6.

Please address all correspondence in this application to the undersigned as attorney of record at 6136 West Kimberly Way, Glendale, AZ 85308.

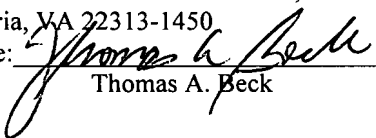
Respectfully Submitted,


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I hereby certify that this paper is being transmitted via the United States Postal Service, in a sealed envelope, postage prepaid, on the date indicated below, addressed to Commissioner of Patents & Trademarks, Post Office Box 1450, Alexandria, VA 22313-1450.

Signature:

Name:


Thomas A. Beck

Date: November 16, 2007